



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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RH Series Series RH14-14-06

Thermoelectric Modules



The RH Series is an annular thermoelectric module (TEM) that is round in shape. The hot and cold side ceramics have a circular hole in the center to accommodate light protrusion for optics, mechanical fastening or temperature probe.

This product line is available in multiple configurations. Assembled with Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics, the RH Series is designed for higher current and larger heat-pumping applications.

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FEATURES

- Center hole
- Precise temperature control
- Reliable solid state operation
- No sound or vibration
- DC operation
- RoHS compliant

APPLICATIONS

- Analytical instrumentation
- Clinical diagnostics
- Photonics laser systems
- Industrial instrumentation
- Food & beverage cooling
- Consumer appliances

SPECIFICATIONS

TECHNICAL		
Hot Side Temperature (°C)	25°C	50°C
Qmax (Watts)	5.7	6.2
Delta Tmax (°C)	67	75
Imax (Amps)	6.0	6.0
Vmax (Volts)	1.7	1.8
Module Resistance (Ohms)	0.25	0.28

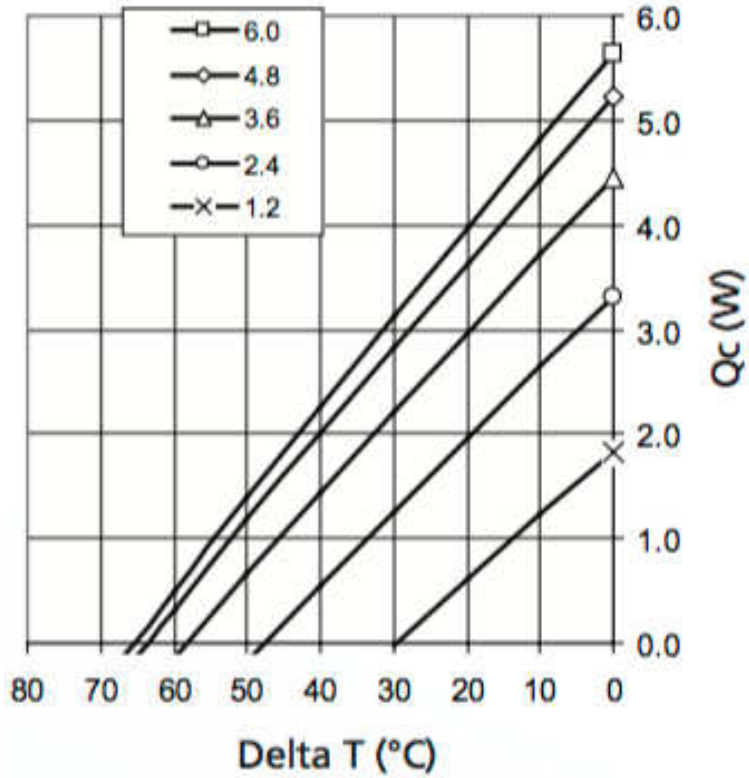
SUFFIX	THICKNESS (PRIOR TO TINNING)	FLATNESS & PARALLELISM	HOT FACE	COLD FACE	LEAD LENGTH
L	0.150"±0.010"	0.0015"/0.0015"	Lapped	Lapped	4.5"
L1	0.150"±0.001"	0.001"/0.001"	Lapped	Lapped	4.5"
L2	0.150"±0.0005"	0.0005"/0.0005"	Lapped	Lapped	4.5"
MM	0.158"±0.010"	0.002"/0.002"	Metallized	Metallized	4.5"

SEALING OPTIONS

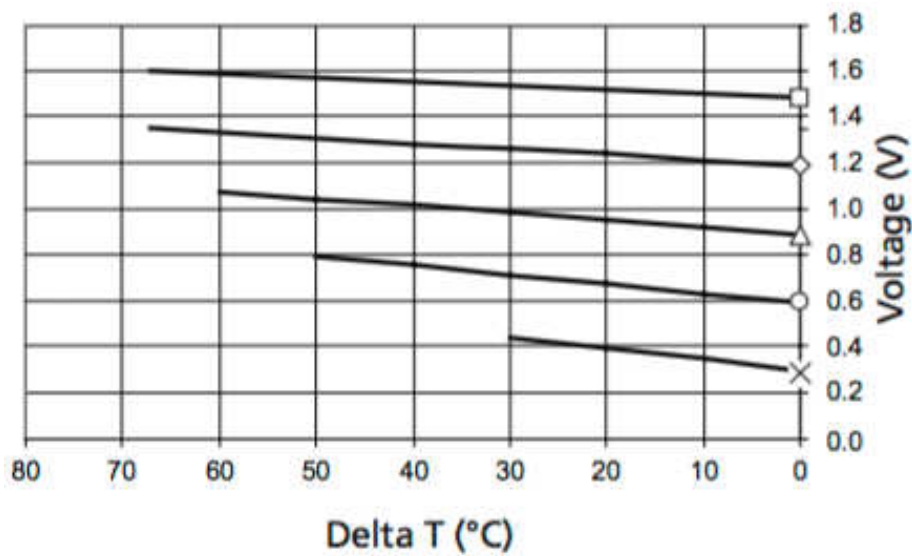
SUFFIX	SEALANT	COLOR	TEMP RANGE	DESCRIPTION
RT	RTV	White	-60 to 204 °C	Non-corrosive, silicone adhesive
EP	Epoxy	Black	-55 to 150 °C	Low density syntactic foam epoxy encapsulant

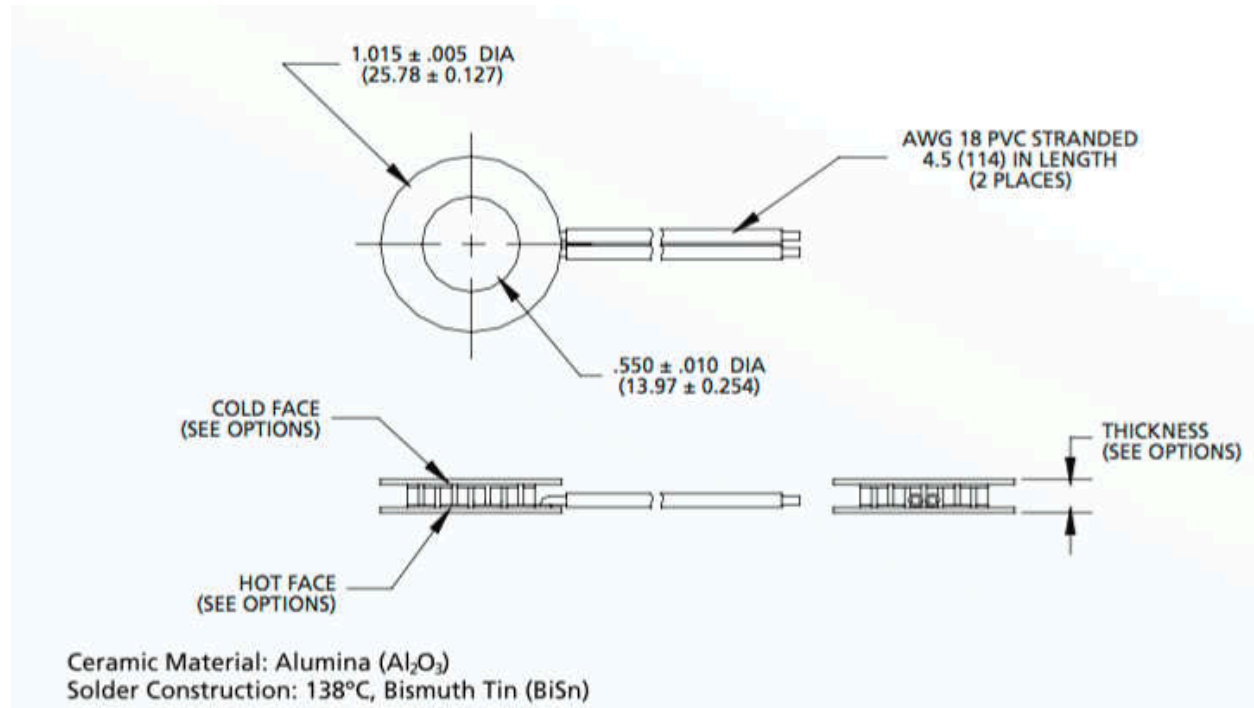
Performance Curves at $T_h = 25^\circ\text{C}$

THERMO



ELECTRIC





NOTES

1. Max operating temperature: 80°C
2. Do not exceed I_{max} or V_{max} when operating module
3. Reference assembly guidelines for recommended installation
4. Solder tinning also available on metallized ceramics

Laird-ETS-RH14-14-06-Data-Sheet-091316

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